

Isolation Voltage	V_{iso}	3750	V_{rms}
Operating Temperature	T_{opr}	-55~+110	
Storage Temperature	T_{stg}	-55~+125	
Soldering Temperature	T_{sol}	260	

NOTE1 100 s pulse, 100Hz frequency

NOTE2 AC for 1minute, R.H.=40~60%

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F=10mA$	-	-	1.4	V
	Reverse Current	I_R	$V_R=6V$	-	-	1	A
	Terminal Capacitance	C_t	$V=0, f=1kHz$	-	10	-	pF
Output	Collector-Emitter dark current	I_{CEO}	$V_{CE}=10V, I_F=0$	-	-	100	nA
	Collector-Emitter breakdown voltage	BV_{CEO}	$I_C=0.1mA, I_F=0$	40	-	-	V
	Emitter-Collector breakdown voltage	BV_{ECO}	$I_E=0.1mA, I_F=0$	6	-	-	V
Transfer Characteristics	Current transfer ratio	CTR	$I_F=1mA, V_{CE}=2V$	600	-	7500	%
	Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_F=20mA, I_C=5mA$	-	0.8	1	V
	Isolation resistance	R_{IO}	DC500V 40~60%R.H.	10^{12}	10^{14}	-	
	Floating Capacitance	C_{IO}	$V=0, f=1MHz$	-	0.4	1	pF
	Cut-off Frequency	f_c	$V_{CE}=5V, I_C=10mA, R_L$ -3dB	-	1	-	kHz
	Rise Time	t_r	$V_{CE}=2V, I_C=10mA, R_L$	-	95	300	s
	Fall Time	t_f		-	84	250	s

Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

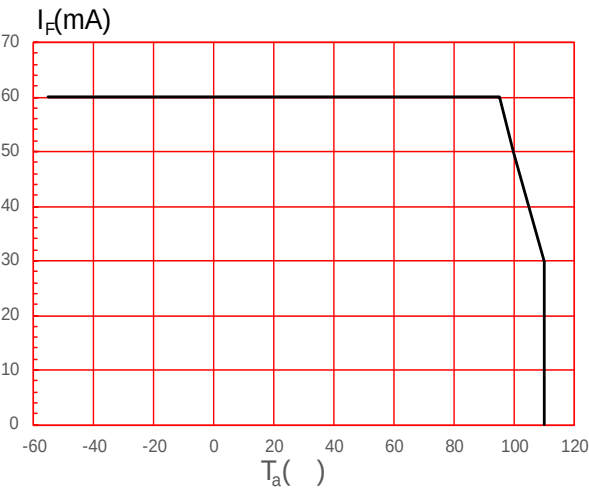


FIG.2: Collector Power Dissipation vs. Ambient Temperature

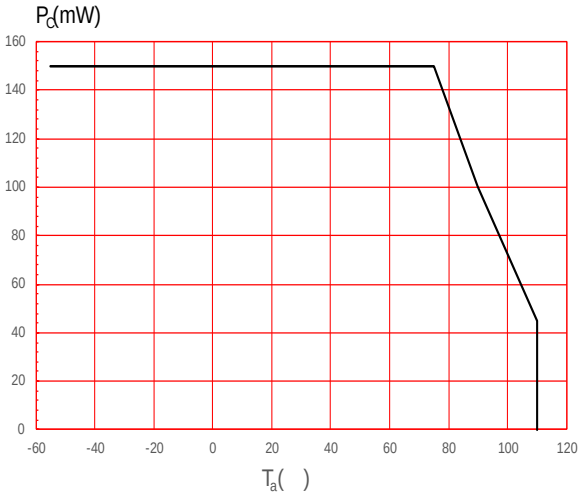


FIG.3: Forward Current vs. Forward Voltage

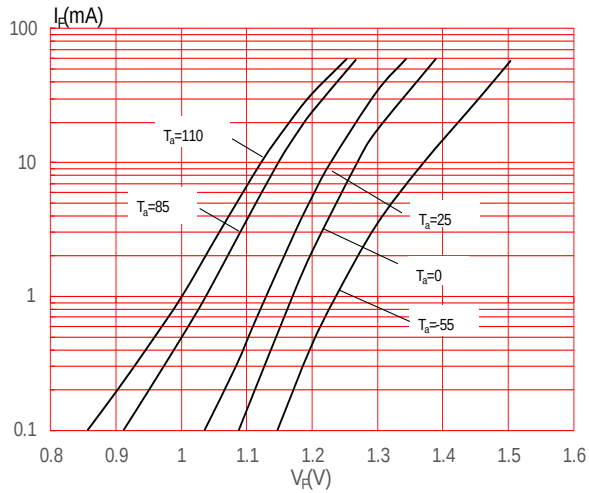


FIG.4: Collector Dark Current vs. Ambient Temperature

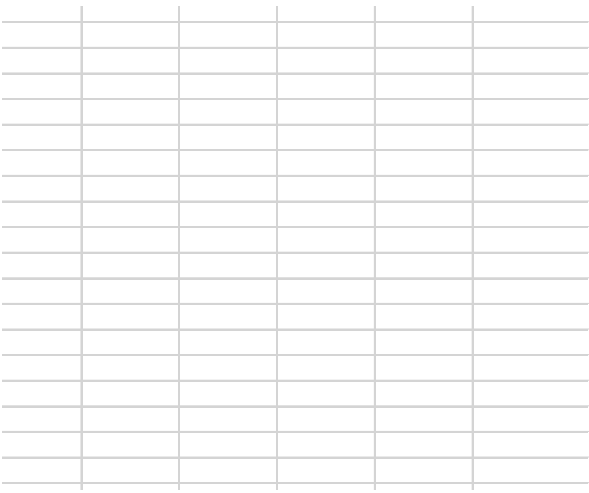


FIG.7: Normalized Current Transfer Ratio vs. Forward Current

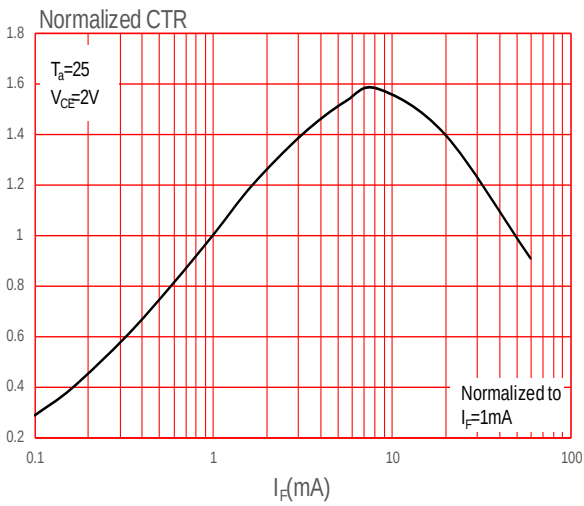


FIG.9: Collector-emitter Saturation Voltage vs. Ambient Temperature

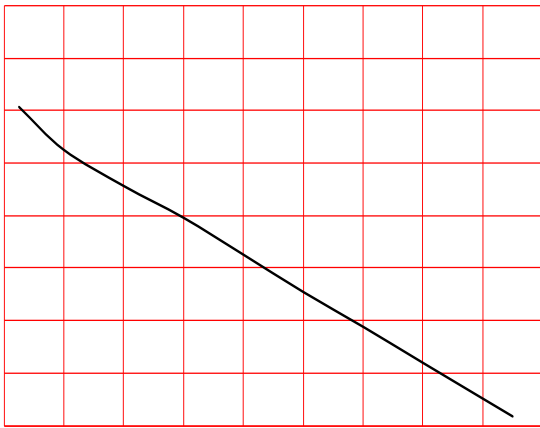


FIG.8: Normalized Current Transfer Ratio vs. Ambient Temperature

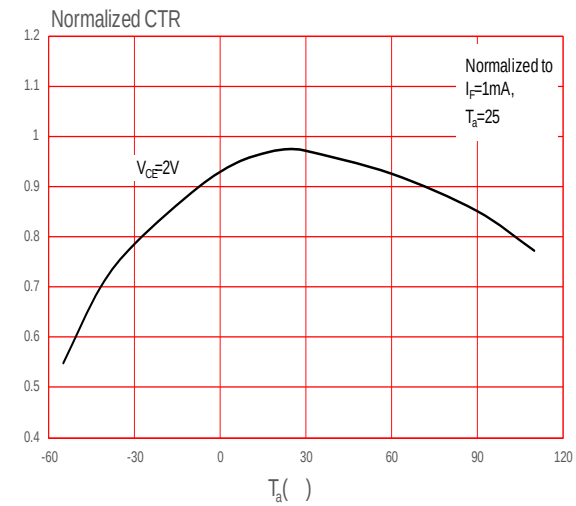


FIG.10: Response Time vs. Load Resistance

Test Circuits

FIG.12: Test Circuits of Response Time

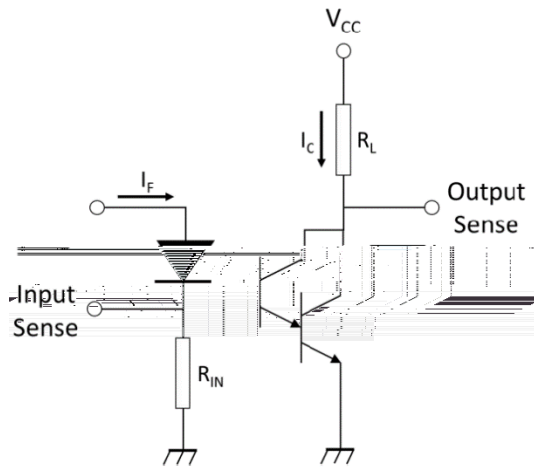


FIG.13: Curves of Response Time

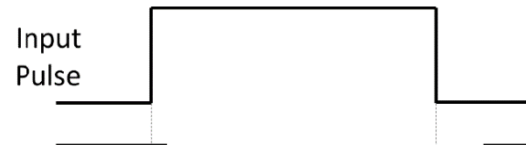
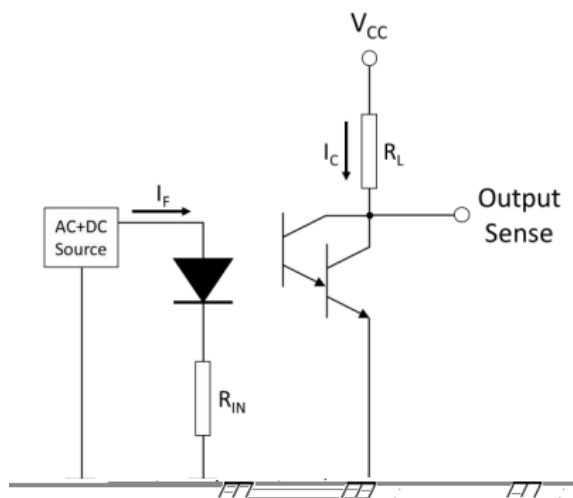
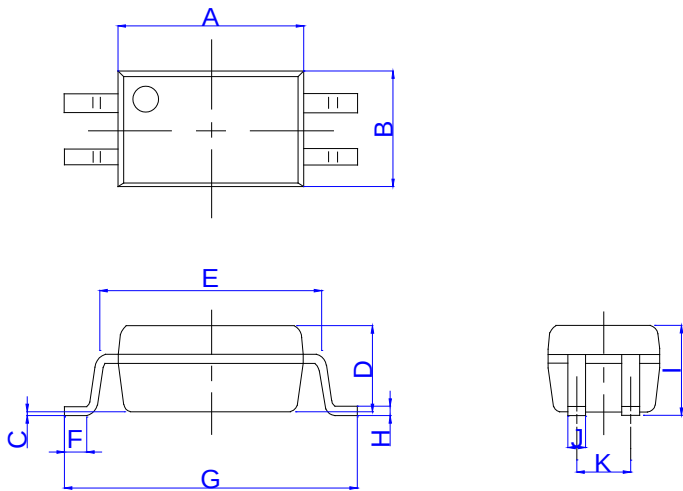


FIG.14: Test Circuits of Frequency Response



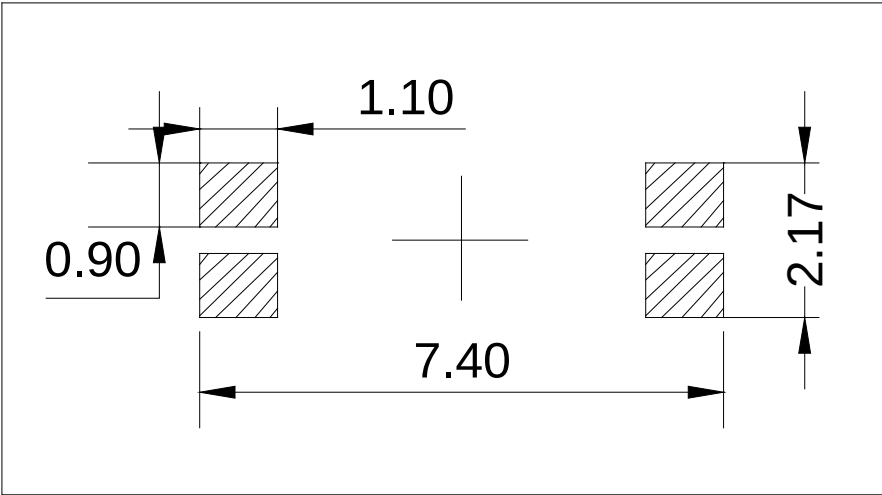
Package Dimension (Unit:mm)

Standard SSOP4 Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.20		4.60	0.166		0.182
B	2.50		2.90	0.099		0.115
C		0.10			0.004	
D	1.90		2.10	0.075		0.083
E	4.90		5.50	0.194		0.217
F		0.50			0.020	
G	6.70		7.30	0.265		0.289
H		0.20			0.008	
I		2.10			0.083	
J		0.40			0.016	
K		1.27			0.050	

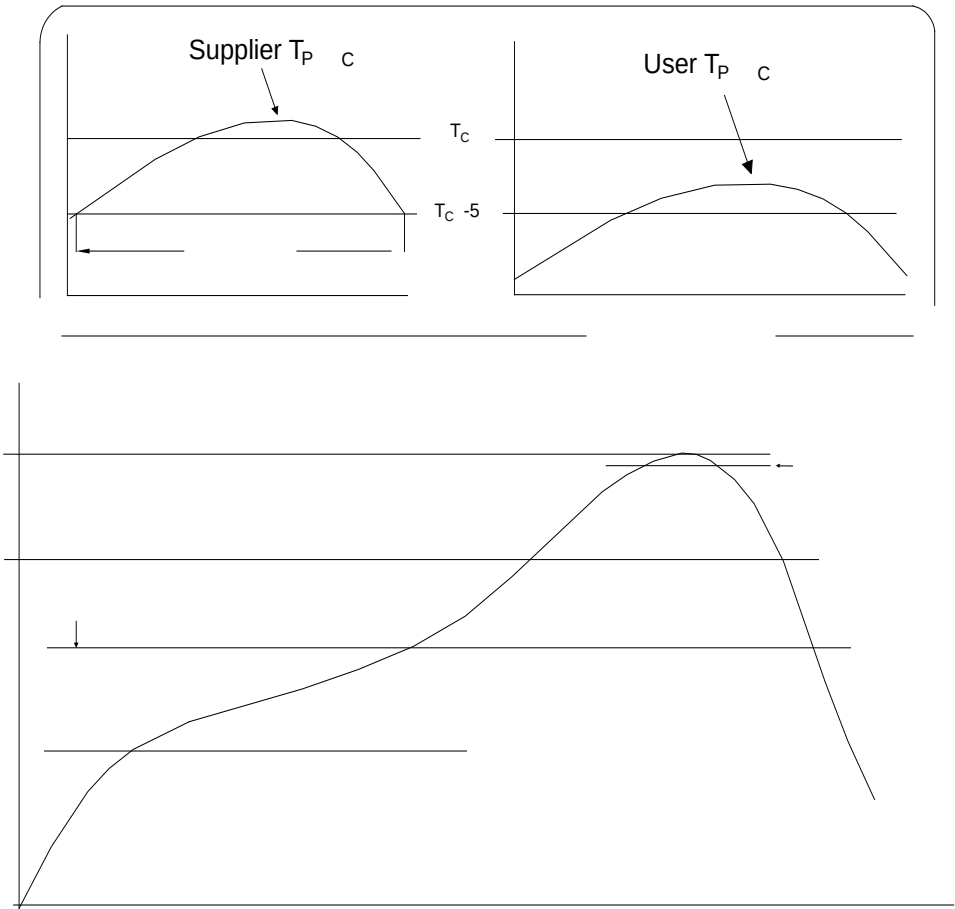
RECOMMENDED SOLDER MASK DIMENSIONS in mm unless otherwise stated



CARRIER TAPE SPECIFICATIONS (Dimensions unless otherwise stated)

Option T1

REFLOW INFORMATION 045 (II)



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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